

Title (en)
DEVICE FOR SINTERING, REMOVING MATERIAL AND/OR LABELING BY MEANS OF ELECTROMAGNETICALLY BUNDLED RADIATION

Title (de)
VORRICHTUNG ZUM SINTERN, ABTRAGEN UND/ODER BESCHRIFTEN MITTELS ELEKTROMAGNETISCHER GEBÜNDELTER STRAHLUNG

Title (fr)
DISPOSITIF DE FRITTAGE, DE GRAVURE ET/OU D'ECRITURE PAR L'INTERMEDIAIRE DE RAYONNEMENT ELECTROMAGNETIQUE EN FAISCEAU

Publication
EP 1330349 A1 20030730 (DE)

Application
EP 01992636 A 20011030

Priority
• DE 0104056 W 20011030
• DE 10053741 A 20001030

Abstract (en)
[origin: US2004045941A1] The invention relates to a device for sintering, removing material and/or labeling by means of electromagnetically bundled radiation, especially to a laser sintering machine and/or a laser surface-processing machine. Said device comprises a construction space (3) which is accommodated in a machine housing (2) and in or above which the following are located: a light-guiding device, especially a scanner (4), into which the beam of a sintering energy source is coupled; a vertically displaceable workpiece platform (7); and a material supply device comprising a coater (9) for supplying sintering material from a supply container (8) to the process area above the workpiece platform (7). Said workpiece platform (7) is a changeable element which can be removed from the construction space (3). The vertically displaceable workpiece platform (7), the supply container (8) and the coater (9) are configured in such a way that they can be removed together from the construction space (3) in the form of a changeable process platform unit (10). Other changeable process platform units (10) with the same or different configurations can be introduced into the construction space (3) in order to carry out the same or different processing operations.

IPC 1-7
B29C 67/00

IPC 8 full level
B29C 67/00 (2006.01); **B23K 26/02** (2006.01); **B23K 26/08** (2006.01); **B23K 26/34** (2014.01); **B23K 37/047** (2006.01); **C04B 35/64** (2006.01)

CPC (source: EP US)
B23K 26/02 (2013.01 - EP US); **B23K 26/0838** (2013.01 - EP US); **B23K 26/34** (2013.01 - EP US); **B23K 37/047** (2013.01 - EP US);
B29C 64/153 (2017.07 - EP US)

Citation (search report)
See references of WO 0236330A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
US 2004045941 A1 20040311; AT E264181 T1 20040415; DE 10053741 C1 20020221; DE 50102015 D1 20040519; EP 1330349 A1 20030730; EP 1330349 B1 20040414; ES 2218466 T3 20041116; JP 2004516166 A 20040603; JP 4289882 B2 20090701; TR 200401495 T4 20040823; WO 0236330 A1 20020510

DOCDB simple family (application)
US 41539103 A 20030922; AT 01992636 T 20011030; DE 0104056 W 20011030; DE 10053741 A 20001030; DE 50102015 T 20011030; EP 01992636 A 20011030; ES 01992636 T 20011030; JP 2002539120 A 20011030; TR 200401495 T 20011030